

C0805X242FATACTU

Aliases (C0805X242FATAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 2,400 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0805, 0.6 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	11 mg	
Shelf Life	78 Weeks	
MSL	1	

2,400 pF

1 kHz 1.0Vrms

100 GOhms

Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	0.6mm MIN
В	0.5mm +/-0.25mm

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W	1.25mm +/-0.3mm	Tolerance	1%
Т	0.78mm +/-0.20mm	Voltage DC	250 VDC
S	0.6mm MIN	Dielectric Withstanding Voltage	625 VDC
В	0.5mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity	4000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
		Dissipation Factor	0.1% I KHZ I.OVIIIIS
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Specifications

Measurement Condition

Insulation Resistance

Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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